

AMENDMENT TO THE SPECIFICATION

The paragraph commencing at page 13, line 6 is amended as follows:

Fig. 4 is an exploded perspective drawing showing the optical module according to the third embodiment of the present invention, and the point of difference between the optical module according to this embodiment and the optical module according to the first embodiment is that, in contrast to the first embodiment in which there is a structure in which a silicon optical waveguide 4 is formed such that the optical waveguide substrate 1 has a plurality of cores 4a buried in a clad 4b on the Si substrate 3, in the optical module according to the present embodiment, the steps 5 and 5, like those of the first embodiment, are formed using anisotropic etching on both sides of a Si sub-mount (a substrate providing an optical element) 31 on which is mounted ~~on the~~ a semiconductor laser 21, this Si sub-mount 31 is inserted in the optical fiber connecting end member 2, position alignment is carried out such that the light emitting surface of the semiconductor laser 21 is flush with the end surface 11a of the optical fiber connection end member 2, and this Si sub-mount 31 is fixed to the optical fiber connecting end member 2 by an adhesive and the like.